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Assistant Commissioner for Patents,
Washington, D.C., 20231, on 12/16/01

Deborah W. Werfocur

Duplicate

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Applicant: K. Sahota, D. Schonauer, J. Groschopf,)
G. Marxsen, and S. Avanzino,) Grp Art Unit: 1765
)
Assignee: Advanced Micro Devices, Inc.) Exam: L. Umez Eronini
)
Serial Number: 09/749,191)
)
Filed: December 26, 2000)
)
For: PREVENTION OF PRECIPITATION)
DEFECTS ON COPPER INTER-)
CONNECTS DURING CMP BY USE)
OF SOLUTIONS CONTAINING)
ORGANIC COMPOUNDS WITH)
SILICA ADSORPTION AND COPPER)
CORROSION INHIBITING)
PROPERTIES)

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MAR 27 2002

TC 1700

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FEB 20 2002
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Assistant Commissioner for Patents
Washington, D.C. 20231

RESPONSE TO RESTRICTION REQUIREMENT

Dear Sir,

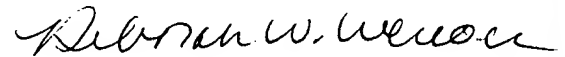
This is in response to the Office Action mailed on November 27, 2001.

The Examiner has required restriction to either: slurry composition claims 1-55, or method claims 56 – 73. Applicant respectfully traverses this restriction requirement. The slurry composition claims specifically recite the slurry's use in polishing Ta layers in integrated circuit metallization systems. It is therefore

submitted that the product can only be used according to the claimed process, and that the process is specifically directed to the claimed product.

In the event that the traverse is not successful, Applicant provisionally elects method claims 56 – 73.

Respectfully submitted,



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